Unfiltered low profile jack in RJ11 and RJ45 models. Shielded and unshielded models available.

Specifications

Cont	act	S
Mata	rial	

Material: Phosphor bronze
Plating: 50 microinches gold
Barrier underplating: 100 microinches nickel

Resistance:

Initial: 20 milliohms maximum

After durability testing

(500 mating cycles): 30 milliohms maximum

PCB Terminals

Solderability 60/40

Shield Material

Solder-plated phosphor bronze

Housing Material

Black glass-filled polyester (Valox 457)

Dielectric Withstanding Voltage

Line-to-line and line-to-ground 1000VAC for 60 seconds

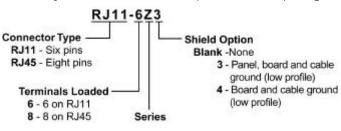
Printed Circuit Board Retention

Before soldering: 1 lb. minimum
After soldering: 20 lb. minimum



Ordering Information

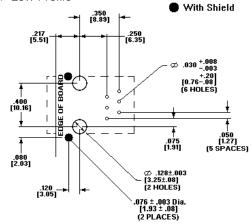
Consult your local Corcom sales representative for pricing.



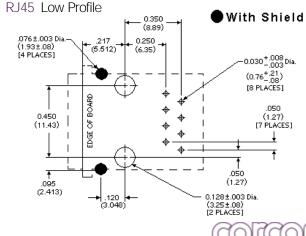
Available Part Numbers			
RJ11-6Z	RJ45-8Z		
RJ11-6Z3	RJ45-8Z3		
RJ11-674	RJ45-874		

PC Board Layout

RJ11 Low Profile



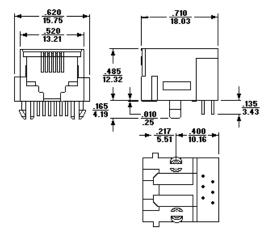
PC Board Layout



Z Series

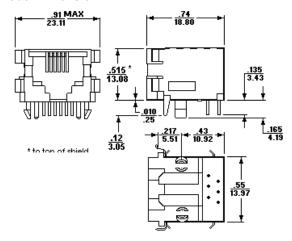
RJ11 Low Profile (No Shield)

Model Dimension



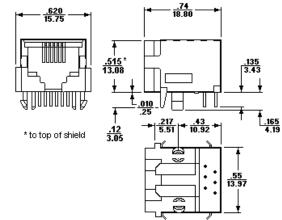
RJ11 Low Profile (Style 3 Shield)

Model Dimension



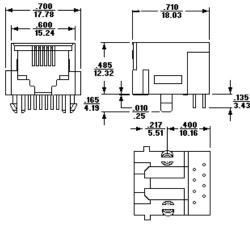
RJ11 Low Profile (Style 4 Shield)

Model Dimension



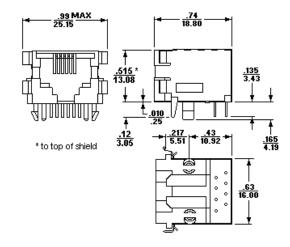
RJ45 Low Profile (No Shield)

Model Dimension



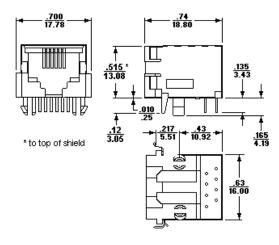
RJ45 Low Profile (Style 3 Shield)

Model Dimension



RJ45 Low Profile (Style 4 Shield)

Model Dimension



Z 38